

FIG. 1A

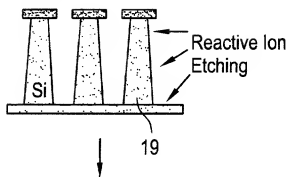


FIG. 1G

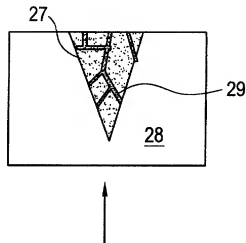


FIG. 1B

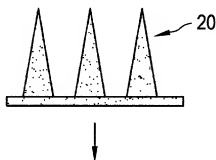


FIG. 1F

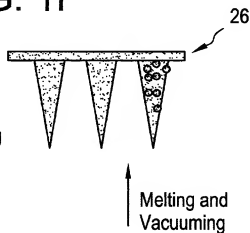


FIG. 1C

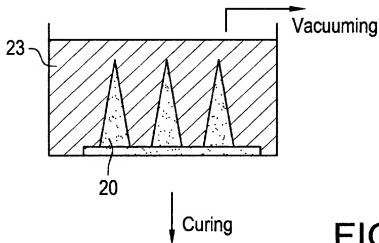


FIG. 1E

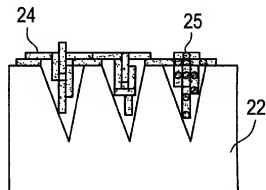


FIG. 1D



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FIG. 2A



FIG. 2B

Aluminum deposition

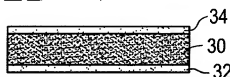


FIG. 2C

Photoresist Coating

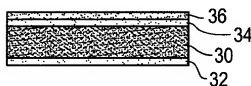


FIG. 2D

UV Exposure

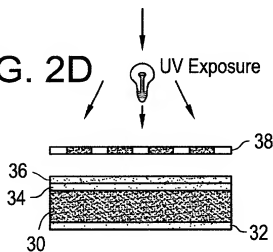


FIG. 2G

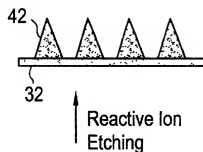


FIG. 2E

Developing

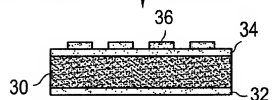


FIG. 2F

Al etching

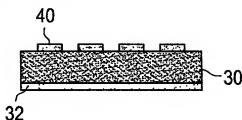


FIG. 3

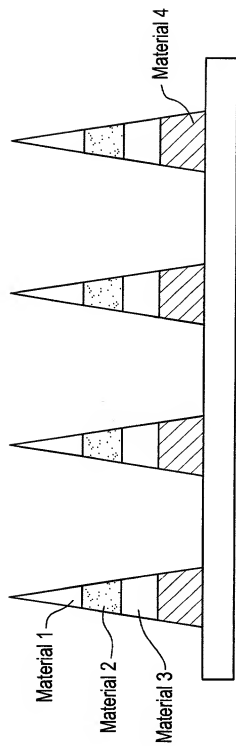
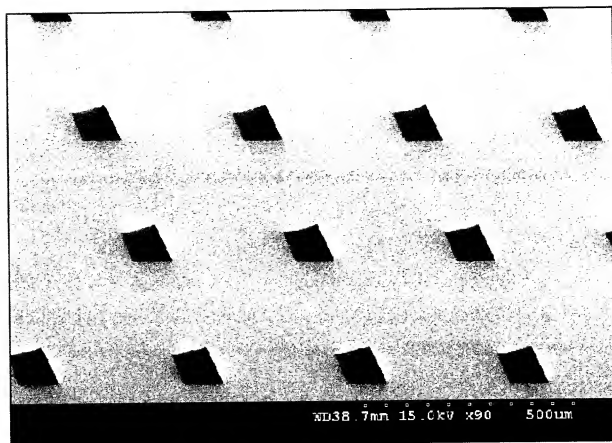
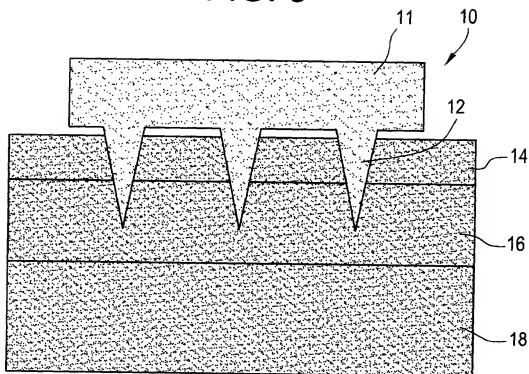


FIG. 4



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FIG. 5



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FIG. 6A

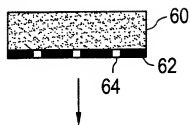


FIG. 6B

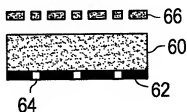
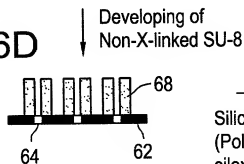


FIG. 6C



FIG. 6D

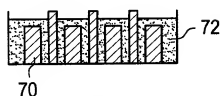


Developing of
Non-X-linked SU-8

FIG. 6G



FIG. 6F



Molding

FIG. 6E



Silicone mold
(Poly-dimethyl
siloxane)

FIG. 7A

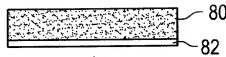


FIG. 7B

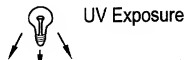


FIG. 7C

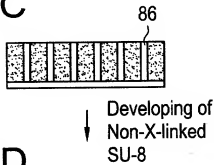


FIG. 7D



FIG. 7E

Metal Deposition



FIG. 7F

Filling up with SU-8

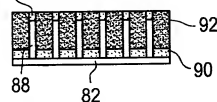


FIG. 7L

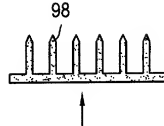


FIG. 7J

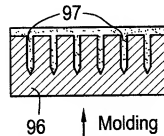


FIG. 7I

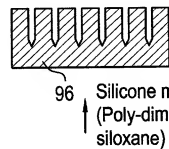


FIG. 7H

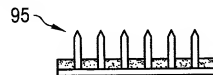
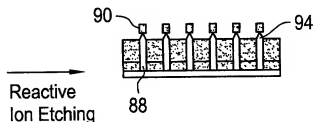


FIG. 7G

Developing



Reactive Ion Etching

FIG. 8A

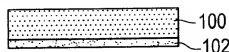
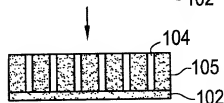
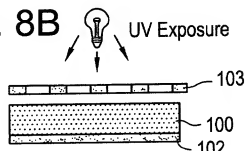


FIG. 8B UV Exposure



Developing

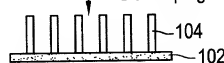


FIG. 8C

Sacrificial polymer layer

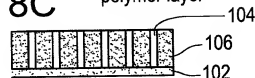


FIG. 8D

Metal Deposition

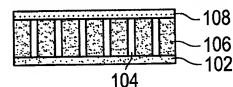


FIG. 8E

Photolithographic work

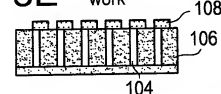


FIG. 8I

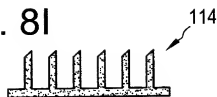
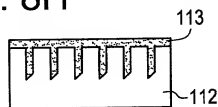


FIG. 8H



Molding



Silicone mold
(Poly-dimethyl
siloxane)

FIG. 8G



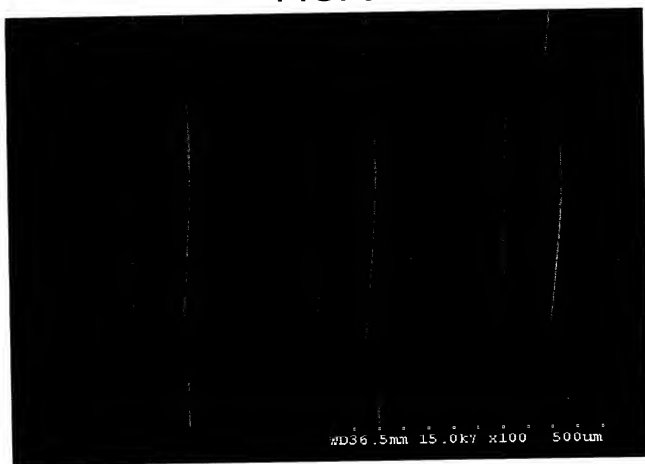
Removing
sacrificial polymer layer

FIG. 8F

Reactive
Ion Etching



FIG. 9



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FIG. 10A

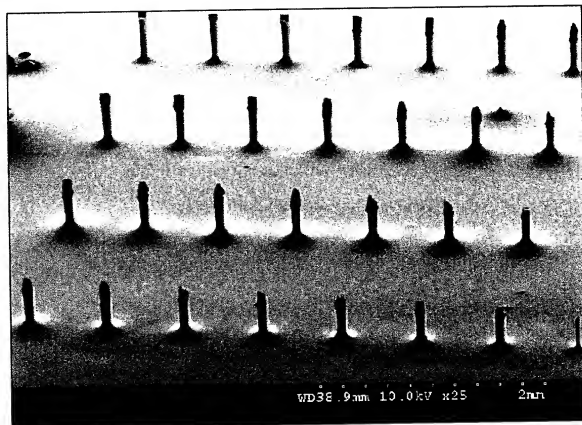


FIG. 10B

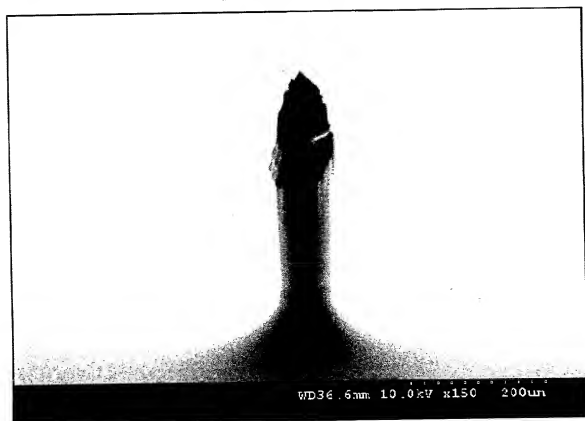


FIG. 11A

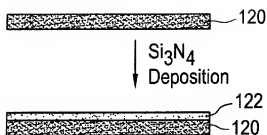


FIG. 11B

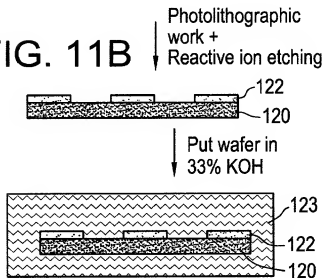


FIG. 11C

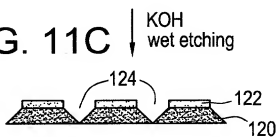
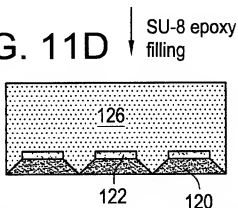


FIG. 11D



Photolitho-
graphic work

FIG. 11G

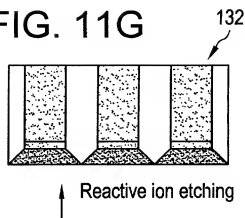


FIG. 11F

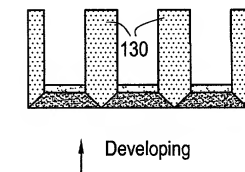
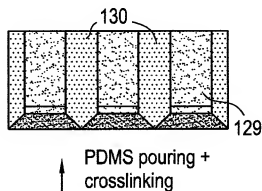


FIG. 11E

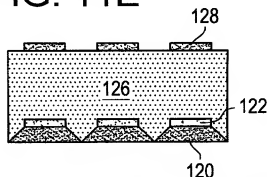
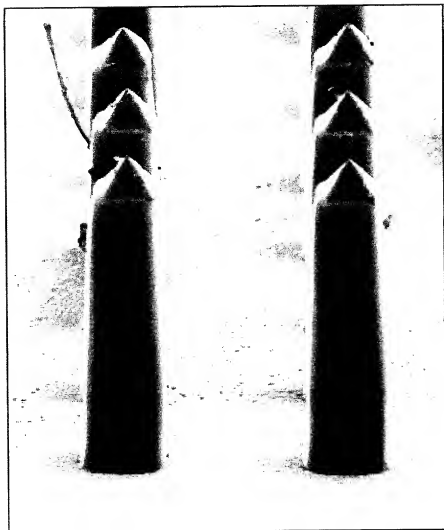


FIG. 12



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